

# Specifications for Approval

Customer Part No.:

Inhere Part No.: LPT50341-001

Part Name: 5mm 圆头有边黑色胶体接收管 LED

Spec Issue Date: 2018-07-17

Revision No.: A

To Customer:

We submit herewith the following information for your approval:

- Sample       OQC Inspection Record       LED Dimension  
 Electrical Characteristics Curve       Internal Circuit Diagram  
 Soldering recommendation

Prepared by: Lily

Date: 2018-07-17

Checked by: Tom

Date: 2018-07-17

Approved by: Wangxiaojun

Date: 2018-07-17

Customer Opinion

- Approve and no objection  
 Reject with the following reason:

**inhere**   
light for your mind  
银河光电

东莞市银河光电有限公司  
DongGuan Inhere Opto CO.,LTD.  
地址:东莞市莞城科技园 D 幢  
ADD:Guancheng Science & Technology Park, DongGuan  
TEL: 0769-23320868 FAX: 0769-23320878  
E-mail: bill@inhereopto.com  
Http://www.inhereopto.com

## SPECIFICATIONS

### Features

- Low power consumption.
- High efficiency and free combinations on the top of LED.
- Good lock and easy to assembly.
- High sensitivity.
- Fast response.
- Versatile mounting on P.C board or panel.
- Stackable and easy to assembly.
- Pb free
- This product doesn't contain restriction Substance, comply RoHS standard

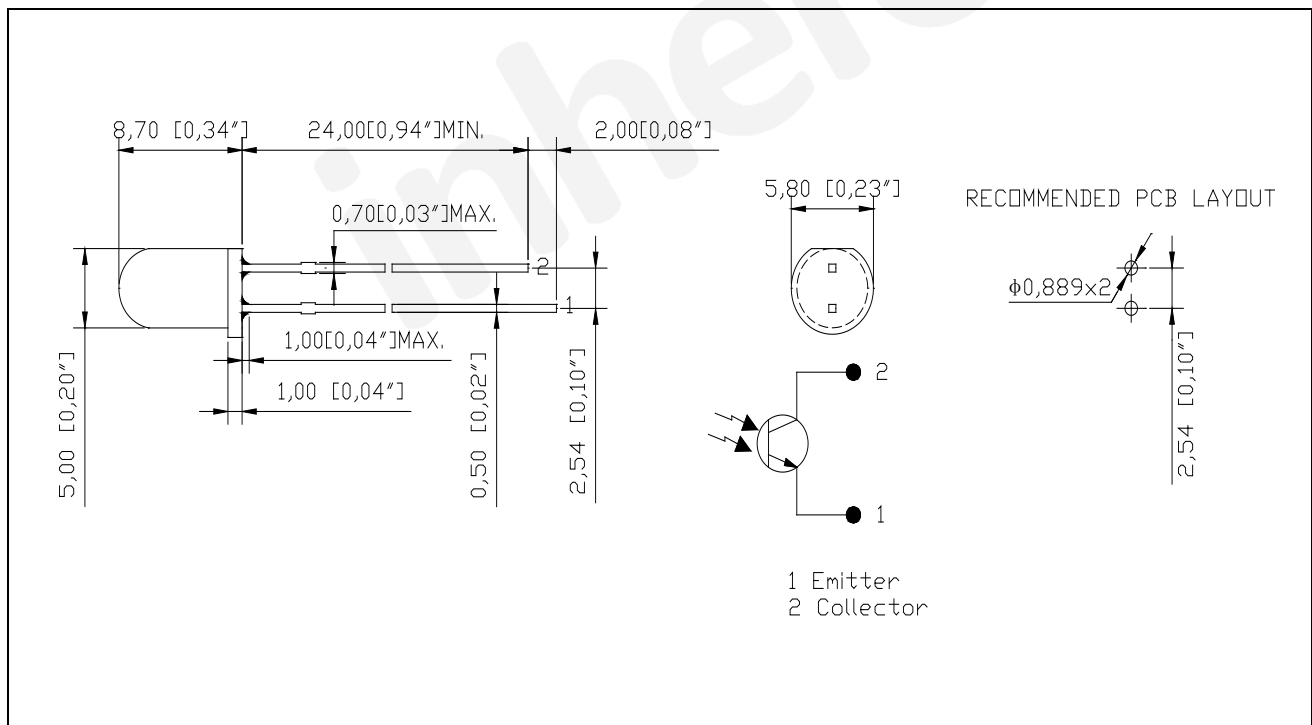
### Description

- This product is a photo transistor which can receive light from the LED, and then change the light into the current, especially infrared light.

### Applications

- Optoelectronic switch.
- Remote controller, Video camera, Mouse.

### Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25$  (0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type
LPT50341-001	Silicon	Black

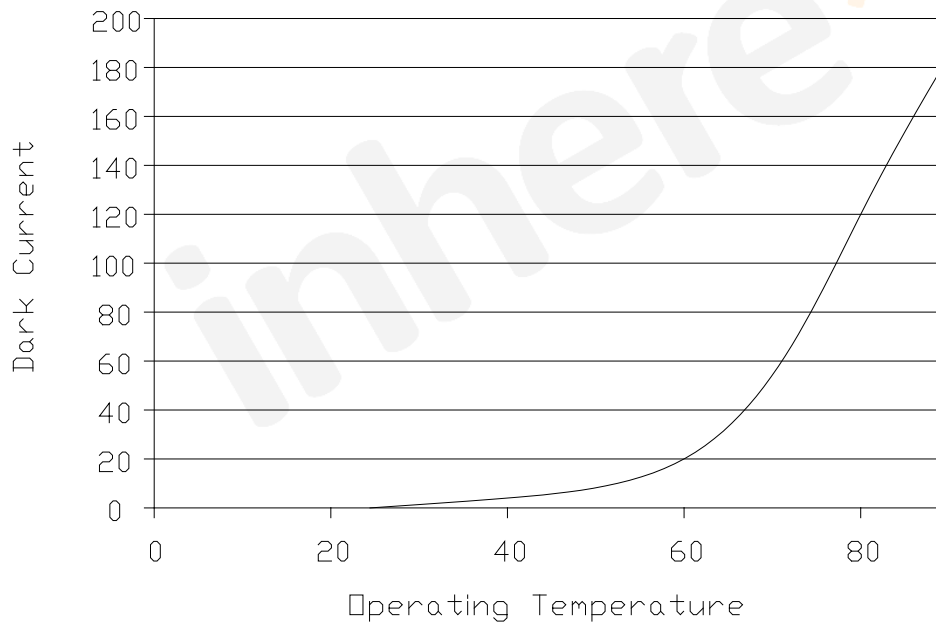
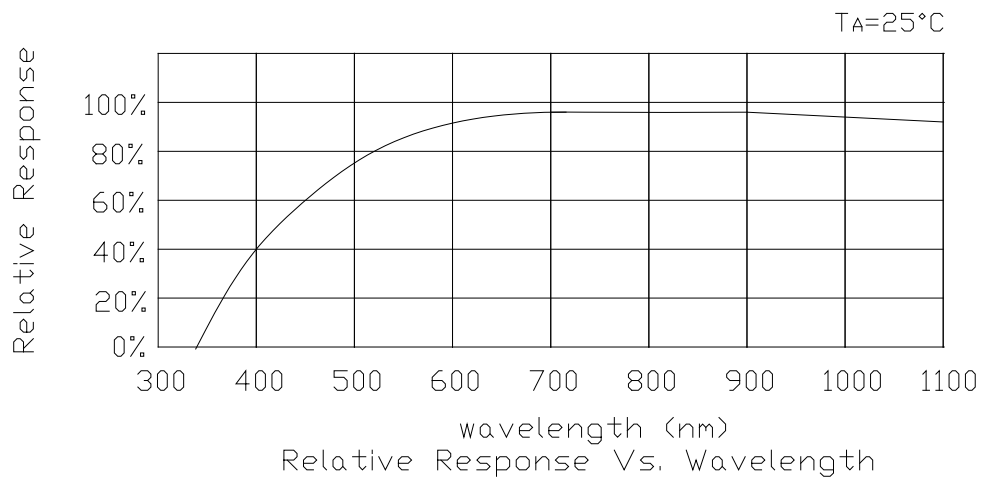
## Electrical / Optical Characteristics (at $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value			Unit	Test Condition
		Min.	Typ.	Max.		
Collector-emitter saturation voltage	VCE (SAT)	--	--	0.4	V	I <sub>ce</sub> =2mA E <sub>e</sub> =1mW/cm <sup>2</sup>
Light current	I <sub>L</sub> (1)	--	0.02	--	μA	V <sub>ce</sub> =5V I <sub>f</sub> =20mA
Collector dark current	I <sub>ceo</sub>	--	--	0.1	μA	V <sub>ce</sub> =5V I <sub>f</sub> =20mA
Wavelength of peak sensitivity	λ <sub>p</sub>	--	940	--	nm	--
Range of spectral bandwidth	λ	400	--	1100	nm	--
Angle of half sensitivity	φ	--	±10	--	deg	--
Rise time / Fall time	t <sub>r</sub> / t <sub>f</sub>	--	15	--	us	V <sub>cc</sub> =5V, I <sub>ce</sub> =1mA, R <sub>L</sub> =1kΩ

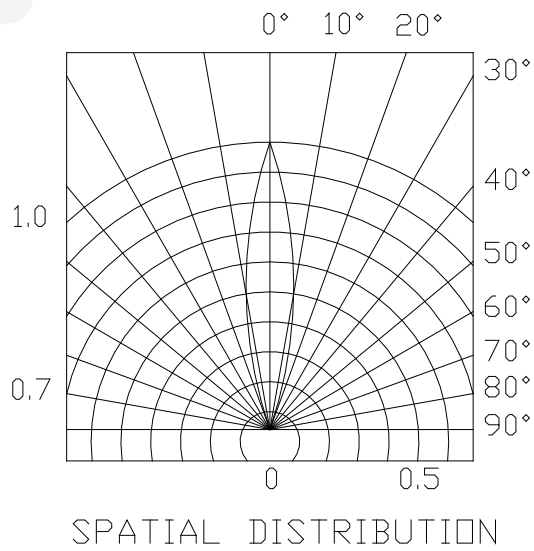
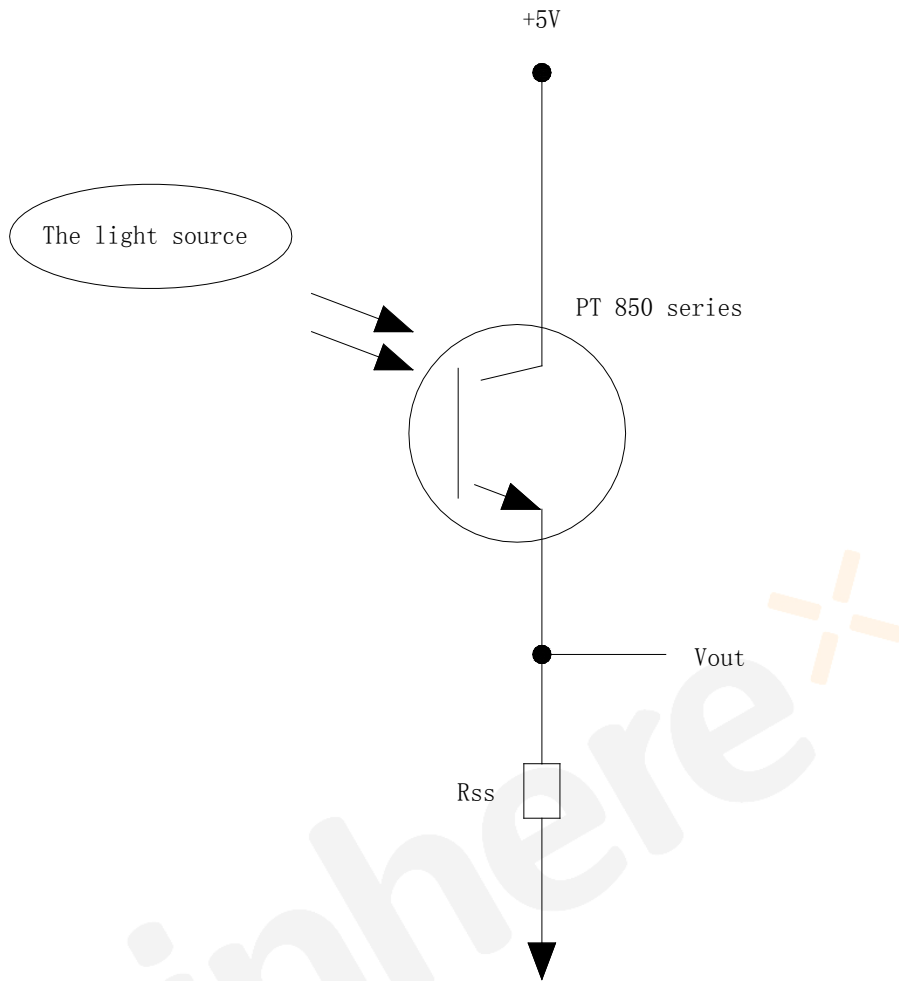
## Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>d</sub>	70	mW
Collector-emitter voltage	V <sub>CEO</sub>	30	V
Emitter-collector voltage	V <sub>ECO</sub>	6	V
Operating Temperature Range	T <sub>opr</sub>	-40~+80	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+85	°C
Lead Soldering Temperature	T <sub>sol</sub>	260°C for 5 SEC (5mm [0.20"] from body)	

**Basic Characteristics (Tamp = 25 ° C, unless otherwise specified)**



Basic characteristics (Tamp = 25 °C, unless otherwise specified)



## Precautions in Use

### 1. Soldering Condition

- a. When soldering, leave the minimum clearance between the bottom of the resin and the soldering point.
- b. Do not solder closer than 3mm from the base of the epoxy bulb.
- c. Maximum allowance soldering conditions are:  
Dip Soldering: 260°C max., 5 sec Max., 1 time.  
Soldering iron: 350°C max., 5 sec Max., 1 time
- d. Contact between molten solder and the resin shall be avoided.
- e. During soldering, do not put any stress on the lead frame, particularly when heated.

### 2. Lead frame Forming and Use

- a. When forming leads, the leads shall be bent at a point at least 3mm from the base of epoxy bulb. Do not use the base of the lead frame as a fulcrum during lead forming.
- b. Lead forming shall be done before soldering.
- c. Do not apply any bending stress to the base of the lead. The stress to the base may damage the LED's characteristics or it may break the LED.
- d. When mounting the LED onto a printed circuit board, the holes on the PCB shall be exactly aligned with the leads of the LED. If the LED is mounted with stress at the leads, it may cause deterioration of the epoxy resin and this may degrade the LED.
- e. Avoid condition which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operation. It is recommended that the LED be used as soon as possible.
- f. Avoid rapid transition in ambient temperature, especially in high humidity environment.

### 3. Static Electricity

- a. The product is sensitive to static electricity charge, and user is required to handle it with care. Particularly, if a current and/or voltage which exceed the Absolute Maximum Rating of the Product is applied, the overflow in energy may cause damage to, or possibly result in electrical destruction of, the LED. The customer is requested to take adequate countermeasure against static electricity charge and surge when handling it.
- b. Proper grounding, use of conductive mat, conductive working uniform and shoes, and conductive containers are effective against static electricity and surge.
- c. Ground low-resistance area where the product contacts, such as metal surface of the work platform, with a conductive mat (surface resistance  $10^6 \sim 10^9 \text{ohm}$ ).
- d. A tip of soldering iron is requested to be grounded. An ionizer shall also be installed where risk of static generation is high.

#### Notes:

1. The above specification and dimensions may be modified for product improvement. Inhere reserves the right to change the specification without notice.
2. When using this product, please observe the Absolute Maximum Ratings and the instructions in the specification sheets. Inhere assumes no responsibility for any damage resulting from use of the product that does not comply with the instructions.